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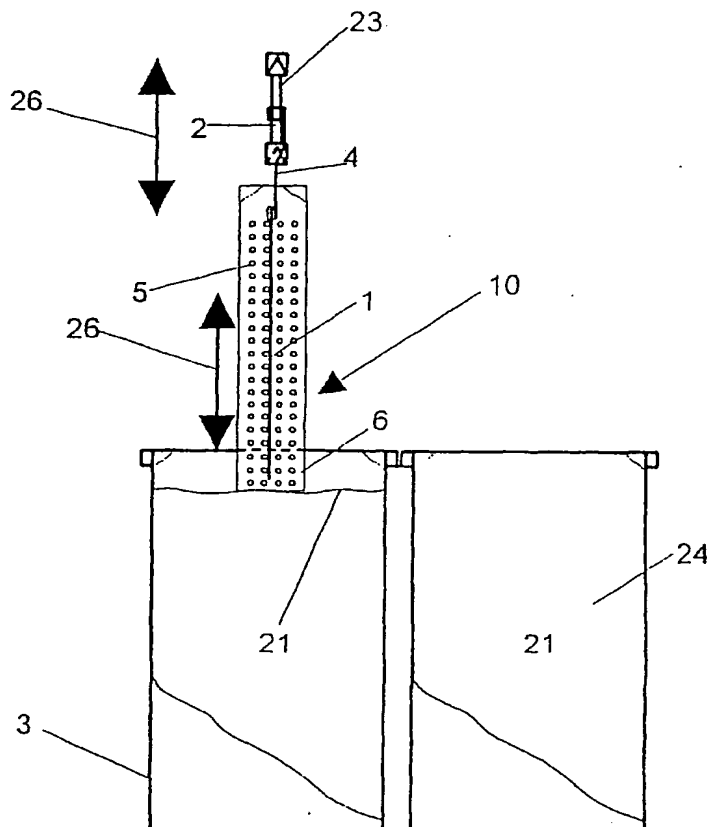
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(54) Title: METHOD AND DEVICE FOR TREATING FLAT AND FLEXIBLE WORK PIECES



(57) **Abstract:** The device in accordance with the invention and the method serve to treat flat and flexible work pieces (1) with a fluid, preferably in electroplating plants and etching facilities. The device and the method permit to place foil-type work pieces (1) in particular in such a manner into the fluid, a wet-chemical or electrochemical processing fluid for example, that the work pieces (1) will not deform or hit the side walls of a processing tank (3) or other built-in components. For this purpose, the processing tank (3) is assigned a protective carrier (5) into which the work pieces (1) are lowered, said carrier (5) being in a largely empty condition. For treatment, the protective carrier (5) is for example lowered into a tank (3) which is filled with processing fluid, said processing fluid flowing into the protective carrier (5). Means are provided on the protective carrier (5) by means of which the processing fluid is allowed to controlledly flow into the protective carrier (5).